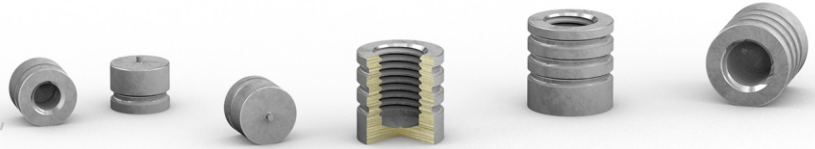




# POWER SOCKET M10

INTERNAL THREAD,  
SMD SOLDERING TECHNOLOGY,  
WITH CENTERING PIN



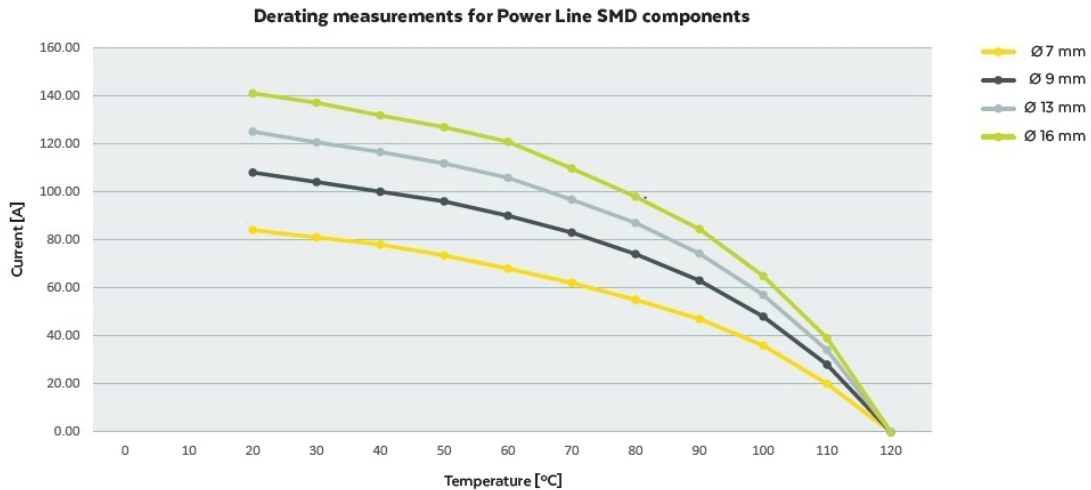
## COMMERCIAL DATA

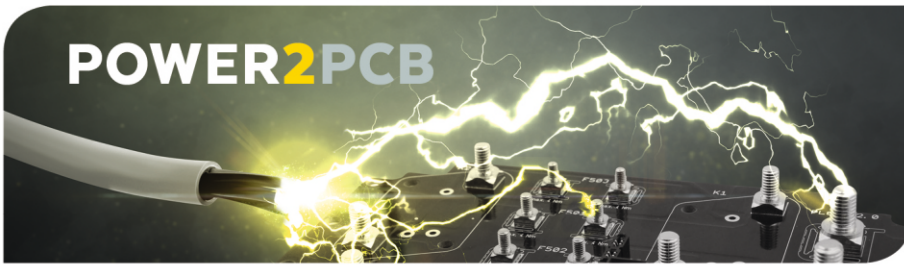
<b>Part number</b>	<b>02.6.0065</b>
<b>Packing unit</b> tape and reel - 2.6.0065.GU	<b>not available yet</b>
<b>Customs tariff number</b>	<b>85369010</b>
<b>Mass</b>	<b>22,14 g</b>
<b>Country of origin</b>	<b>DE (Germany)</b>

## TECHNICAL DATA

<b>Current carrying capacity</b>	<b>ca. 250 A at 20°C / ca. 140 A at 85° C</b>
<b>Material</b>	<b>CuZn39Pb3</b>
<b>Surface</b>	<b>matt tinned</b>

**Derating curves are snapshots under test conditions!**  
Testing was undertaken using two-layer circuit with 70µm copper.



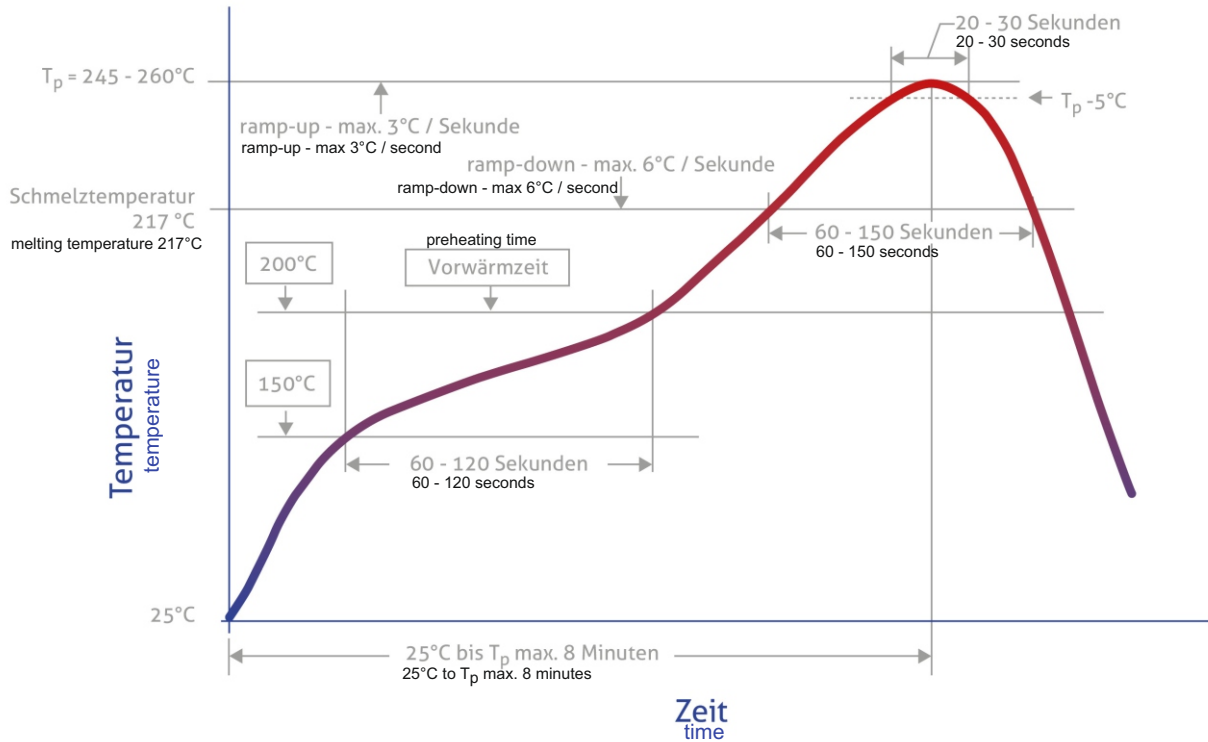


**MTCON**  
NECT  
IVITY

**PROCESSING**

<b>Torque</b>	<b>17,0 Nm</b>
<b>Solder paste thickness</b>	<b>150 µm</b>
<b>Operating temperature</b>	<b>-55°C to 150°C</b>

**SOLDERING PROFILE**



**Reflow Temperatur in Abhängigkeit der Leiterplattendicke:**

Reflow temperature depending on the thickness of the printed circuit board:

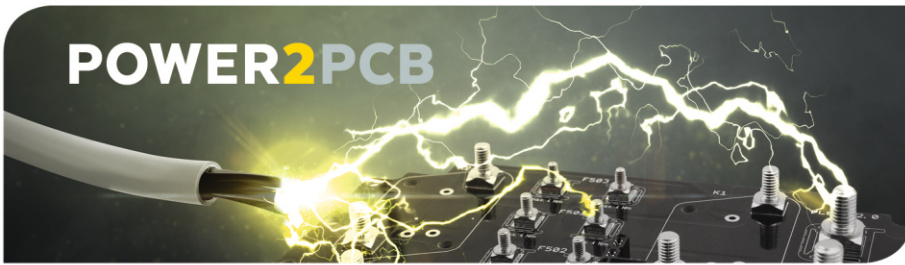
Eigenschaften properties	Volumen $\text{mm}^3 < 350$ volume $\text{mm}^3 < 350$	Volumen $\text{mm}^3 350-2000$ volume $\text{mm}^3 350-2000$	Volumen $\text{mm}^3 > 2000$ volume $\text{mm}^3 > 2000$
Leiterplattendicke (Bleifrei) $< 1.6 \text{ mm}$ PCB thickness (lead free) $< 1.6 \text{ mm}$	260 °C	260 °C	260 °C
Leiterplattendicke (Bleifrei) $1.6 \text{ mm} - 2.5 \text{ mm}$ PCB thickness (lead free) $1.6 \text{ mm} - 2.5 \text{ mm}$	260 °C	250 °C	245 °C
Leiterplattendicke (Bleifrei) $\geq 2.5 \text{ mm}$ PCB thickness (lead free) $\geq 2.5 \text{ mm}$	250 °C	245 °C	245 °C

mit Bezug auf IPC/JEDEC J-STD-020D  
regarding IPC/JEDEC J-STD-020D

**CONFORMITY**

RoHS compliant





■ TAPE AND REEL

not available yet

■ LAYOUT

Lötpad mit Zentrierzapfen  
solder pad with centering pin

